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- Meets TIA/EIA-422-B, TIA/EIA-485-A, and CCITT Recommendations V.11 and X.27
- Low Supply-Current Requirements . . . 30 mA Max
- Driver Output Capacity . . . ±60 mA
- Thermal Shutdown Protection
- Driver Common-Mode Output Voltage Range of -7 V to 12 V
- Receiver Input Impedance . . . 12 kΩ Min
- Receiver Input Sensitivity . . . ±200 mV
- Receiver Input Hysteresis . . . 60 mV Typ
- Receiver Common-Mode Input Voltage Range of ±12 V
- Operates From Single 5-V Supply
- Glitch-Free Power-Up and Power-Down
  Protection

#### description/ordering information

**N OR NS PACKAGE** (TOP VIEW) NC 14 Vcc RΓ 13 🛛 V<sub>CC</sub> 2 RE 3 12 A DE 14 Πв 11 D 10 🛛 Z 5 GND 6 9 🛛 Y GND [ 8 🛛 NC

NC - No internal connection

The SN75ALS181 is a differential driver and receiver pair designed for bidirectional data communication on multipoint bus transmission lines. The design provides for balanced transmission lines and meets TIA/EIA-422-B and TIA/EIA-485-A, and CCITT recommendations V.10, V.11, X.26, and X.27.

The SN75ALS181 combines a 3-state differential line driver and a differential-input line receiver that operate from a single 5-V power supply. The driver and receiver have active-high and active-low enables, respectively, that can be connected together externally to function as a direction control. The driver differential outputs and the receiver differential inputs are connected to separate pins for greater flexibility and are designed to offer minimum loading to the bus when the driver is disabled or  $V_{CC} = 0$ . These ports feature wide positive and negative common-mode voltage changes, making the device suitable for party-line applications.

#### **ORDERING INFORMATION**

TA	PACKAGE <sup>†</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
0°C to 70°C	PDIP (N)	Tube of 25	SN75ALS181N	SN75ALS181N	
	SOP (NS)	Reel of 2000	SN75ALS181NSR	75ALS181	

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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#### **Function Tables**

EACH DRIVER						
INPUT	ENABLE	OUT	PUTS			
D	DE	Y	Z			
Н	Н	Н	L			
L	Н	L	н			
Х	L	Z	Z			

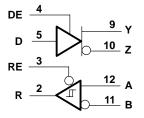
#### EACH RECEIVER

DIFFERENTIAL A–B	EN <u>AB</u> LE RE	OUTPUT Y
$V_{ID} \ge 0.2 V$	L	Н
$-0.2 \text{ V} < \text{V}_{\text{ID}} < 0.2 \text{ V}$	L	?
V <sub>ID</sub> ≤ –0.2 V	L	L
Х	н	z

H = high level, L = low level, ? = indeterminate,

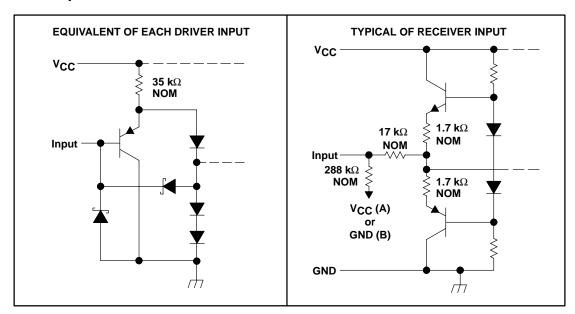
X = irrelevant, Z = high impedance (off)

# logic diagram (positive logic)



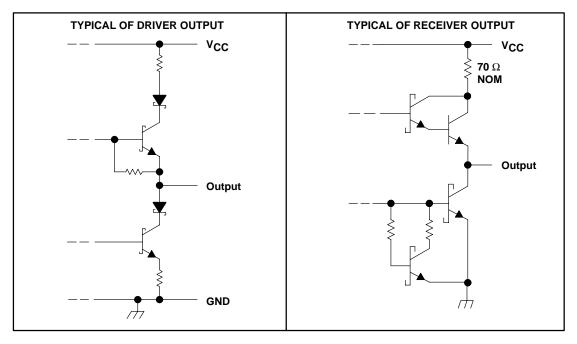


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## schematics of inputs

## schematics of outputs





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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage, V <sub>CC</sub> (see Note 1) Input voltage, D, DE, and RE inputs	
Output voltage range, driver	
Input voltage range, receiver	–14 V to 14 V
Receiver differential input voltage range (see Note 2)	–14 V to 14 V
Package thermal impedance, $\theta_{JA}$ (see Notes 3 and 4): N package	80°C/W
NS package	
Operating virtual junction temperature, T <sub>J</sub>	150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential input voltage, are with respect to network ground terminal.

2. Differential input voltage is measured at the noninverting terminal with respect to the inverting terminal.

- 3. Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.
- 4. The package thermal impedance is calculated in accordance with JESD 51-7.

#### recommended operating conditions

			MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.75	5	5.25	V
Voc	Common-mode output voltage (see Note 5)	Driver	-7		12	V
VIC	Common-mode input voltage (see Note 5)	Receiver	-12		12	V
VIH	High-level input voltage	D, DE, and RE	2			V
VIL	Low-level input voltage	D, DE, and RE			0.8	V
VID	Differential input voltage				±12	V
	High-level output current	Driver			-60	mA
ЮН	nigh-level output current	Receiver			-400	μA
	Low-level output current	Driver			60	mA
<sup>I</sup> OL		Receiver			8	IIIA
Т <sub>А</sub>	Operating free-air temperature		0		70	°C

NOTE 5: The algebraic convention, where the less positive (more negative) limit is designated as minimum, is used in this table for common-mode output voltage level only.



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## **DRIVER SECTION**

# electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT	
VIK	Input clamp voltage	lj = -18 mA	lj = -18 mA			-1.5	V	
VO	Output voltage	I <sub>O</sub> = 0		0		6	V	
VOD1	Differential output voltage	I <sup>O</sup> = 0		1.5		6	V	
		V <sub>CC</sub> = 5 V,		1/2 VOD1				
IVOD2	Differential output voltage	R <sub>L</sub> = 100 Ω	See Figure 1	2			V	
		RL = 54 Ω		1.5	2.3	5		
Vod3	Differential output voltage	$V_{\text{test}} = -7 \text{ V to } 12 \text{ V},$	See Figure 2	1.5		5	V	
$\Delta  V_{OD} $	Change in magnitude of differential output voltage (see Note 6)	$R_L = 54 \Omega$ or 100 Ω,	See Figure 1			±0.2	V	
Vee		See Figure 1			3	V		
Voc	Common-mode output voltage	$R_L = 54 \Omega \text{ or } 100 \Omega$ , See Figure 1				-1		
$\Delta  V_{OC} $	Change in magnitude of common-mode output voltage (see Note 6)	$R_L = 54 \Omega$ or 100 Ω,	See Figure 1			±0.2	V	
I <sub>OZ</sub>	High-impedance-state output current	$V_{O} = -7 V \text{ to } 12 V,$	See Note 7			±100	μA	
Iн	High-level input current	V <sub>IH</sub> = 2.4 V				20	μA	
Ι <sub>Ι</sub>	Low-level input current	V <sub>IL</sub> = 0.4 V				-100	μA	
		$V_{O} = -7 V$ $V_{O} = V_{CC}$				-250		
IOS	Chart size it subsut surgest				250			
	Short-circuit output current	V <sub>O</sub> = 12 V				250	mA	
		V <sub>O</sub> = 0 V				-150		
	Supply current (total package)	No load	Outputs enabled		21	30	mA	
ICC	Supply current (total package)	No load Outputs disa			14	21	ШA	

<sup>†</sup> All typical values are at  $V_{CC} = 5$  V and  $T_A = 25^{\circ}C$ .

NOTES: 6. Δ|V<sub>OD</sub>| and Δ|V<sub>OC</sub>| are the changes in magnitude of V<sub>OD</sub> and V<sub>OC</sub>, respectively, that occur when the input is changed from a high level to a low level.

7. This applies for both power on and power off. Refer to TIA/EIA-485-A for exact conditions.

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST CONDITIONS			MIN	TYP†	MAX	UNIT
<sup>t</sup> dD	Differential output delay time, $t_{dDH}$ or $t_{dDL}$	R <sub>L</sub> = 54 Ω,	C <sub>L</sub> = 50 pF,	See Figure 3	9	13	20	ns
<sup>t</sup> sk(p)	Pulse skew ( t <sub>dDH</sub> – t <sub>dDL</sub>  )	RL = 54 Ω,	C <sub>L</sub> = 50 pF,	See Figure 3		1	8	ns
t <sub>t</sub>	Differential output transition time	R <sub>L</sub> = 54 Ω,	C <sub>L</sub> = 50 pF,	See Figure 3	3	10	16	ns
<sup>t</sup> PZH	Output enable time to high level	R <sub>L</sub> = 110 Ω,	See Figure 4			36	53	ns
<sup>t</sup> PZL	Output enable time to low level	R <sub>L</sub> = 110 Ω,	See Figure 5			39	56	ns
<sup>t</sup> PHZ	Output disable time from high level	R <sub>L</sub> = 110 Ω,	See Figure 4			20	31	ns
<sup>t</sup> PLZ	Output disable time from low level	R <sub>L</sub> = 110 Ω,	See Figure 5			9	20	ns

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$  and  $T_A = 25^{\circ}\text{C}$ .



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## **RECEIVER SECTION**

# electrical characteristics over recommended ranges of supply voltage, common-mode input voltage, and operating free-air temperature (unless otherwise noted)

	PARAMETER	TE	ST CONDITIONS		MIN	TYP†	MAX	UNIT
V <sub>T+</sub>	Positive-going threshold voltage, differential input	V <sub>O</sub> = 2.7 V,	$I_{O} = -0.4 \text{ mA}$				0.2	V
V <sub>T-</sub>	Negative-going threshold voltage, differential input	V <sub>O</sub> = 0.5 V,	I <sub>O</sub> = 8 mA		-0.2			V
V <sub>hys</sub>	Input hysteresis (V <sub>T+</sub> – V <sub>T</sub> _)					60		mV
VIK	Input clamp voltage, RE	lı = -18 mA					-1.5	V
VOH	High-level output voltage	V <sub>ID</sub> = 200 mV,	I <sub>OH</sub> = -400 μA,	See Figure 6	2.7			V
VOL	Low-level output voltage	$V_{ID} = -200 \text{ mV},$	I <sub>OL</sub> = 8 mA,	See Figure 6			0.45	V
IOZ	High-impedance-state output current	$V_{O} = 0.4 \text{ V to } 2.4 \text{ V}$	,				±20	μΑ
łı	Line input current	Other input at 0 V, See Note 7	$V_{I} = 12 V$ $V_{I} = -7 V$				1 -0.8	mA
Iн	High-level input current, RE	VIH = 2.7 V	· ·				20	μA
١ <sub>IL</sub>	Low-level input current, RE	V <sub>IL</sub> = 0.4 V					-100	μΑ
ri	Input resistance				12			kΩ
IOS	Short-circuit output current	V <sub>ID</sub> = 200 mV,	V <sub>O</sub> = 0 V		-15		-85	mA
1	Supply surrent (total package)	Nolood	Outputs enabled			21	30	~
ICC	Supply current (total package)	No load	Outputs disabled			14	21	mA

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$  and  $T_A = 25^{\circ}C$ .

NOTE 7: This applies for both power on and power off. Refer to TIA/EIA-485-A for exact conditions.

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 15 \text{ pF}$ (unless otherwise noted) (see Figure 7)

	PARAMETER	TEST CONDITIONS	MIN	түр†	MAX	UNIT
<sup>t</sup> PHL	Propagation delay time, high- to low-level output	$V_{ID} = -1.5 \text{ V} \text{ to } 1.5 \text{ V}$	10	16	25	ns
<sup>t</sup> PLH	Propagation delay time, low- to high-level output	$V_{ID} = -1.5 \text{ V} \text{ to } 1.5 \text{ V}$	10	16	25	ns
<sup>t</sup> sk(p)	Pulse skew ( tpLH - tpHL )	$V_{ID} = -1.5 \text{ V} \text{ to } 1.5 \text{ V}$		1	8	ns
<sup>t</sup> PZH	Output enable time to high level			7	15	ns
<sup>t</sup> PZL	Output enable time to low level			9	19	ns
<sup>t</sup> PHZ	Output disable time from high level			18	27	ns
<sup>t</sup> PLZ	Output disable time from low level			10	15	ns

<sup>†</sup> All typical values are at  $V_{CC}$  = 5 V and  $T_A$  = 25°C.



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## PARAMETER MEASUREMENT INFORMATION

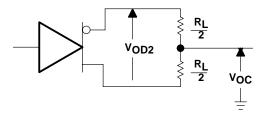


Figure 1. Driver Test Circuit, V<sub>OD</sub> and V<sub>OC</sub>

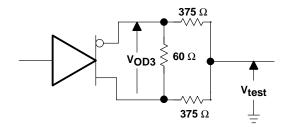
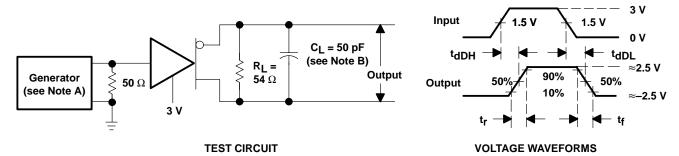


Figure 2. Driver Circuit, VOD3



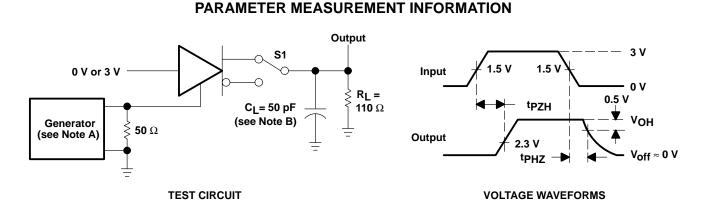
NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, 50% duty cycle, t<sub>f</sub>  $\leq$  6 ns, t<sub>f</sub>  $\leq$  6 ns, Z<sub>O</sub> = 50  $\Omega$ .

B.  $C_{L}$  includes probe and jig capacitance.

### Figure 3. Driver Differential-Output Delay and Transition Times



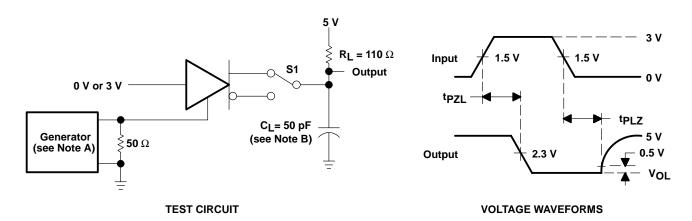
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# NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR $\leq$ 1 MHz, 50% duty cycle, t<sub>r</sub> $\leq$ 6 ns, t<sub>r</sub> $\leq$ 8 ns, t<sub>r</sub>

B. CL includes probe and jig capacitance.





- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, 50% duty cycle, t<sub>r</sub>  $\leq$  6 ns, t<sub>r</sub>  $\leq$  8 ns, t<sub>r</sub>
  - B. CL includes probe and jig capacitance.

#### Figure 5. Driver Enable and Disable Times

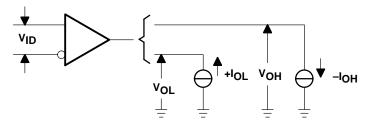
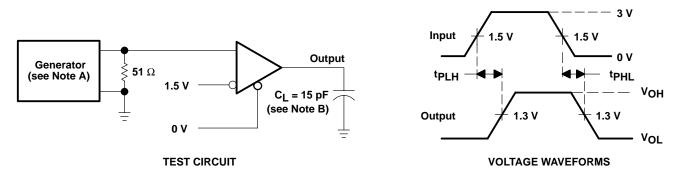


Figure 6. Receiver, VOH and VOL



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## PARAMETER MEASUREMENT INFORMATION



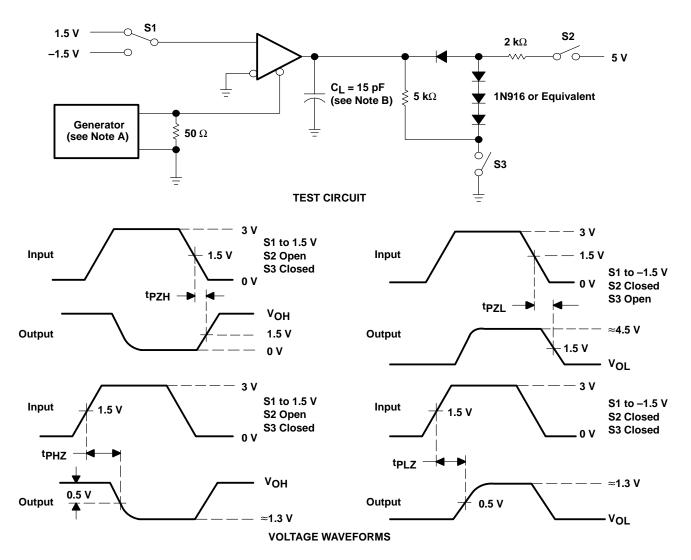
NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, 50% duty cycle, t<sub>r</sub>  $\leq$  6 ns, t<sub>r</sub>  $\leq$  6 ns, Z<sub>O</sub> = 50  $\Omega$ .

B. CL includes probe and jig capacitance.

### Figure 7. Receiver Propagation-Delay Times



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### PARAMETER MEASUREMENT INFORMATION

NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, 50% duty cycle, t<sub>r</sub>  $\leq$  6 ns, t<sub>r</sub>  $\leq$  8 ns, t<sub>r</sub>

B. CL includes probe and jig capacitance.

### Figure 8. Receiver Output Enable and Disable Times



### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN75ALS181N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75ALS181NE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75ALS181NSLE	OBSOLETE	SO	NS	14		TBD	Call TI	Call TI
SN75ALS181NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS181NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

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**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

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<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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# N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



## MECHANICAL DATA

## PLASTIC SMALL-OUTLINE PACKAGE

#### 0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 $\bigcirc$ Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS \*\* 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G\*\*)

**14-PINS SHOWN** 

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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